

Part Number

Customer

Category	Parameter	Specification	Measurement Method
OverallWafer	1.0 Diameter	150.00 +/- 0.20 mm	
	2.0 Primary Flat Orientation	{110} +/- 1 degree	Wafer Vendor
	3.0 Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0 Secondary Flat Orientation	none / semi std	wafer vendor
	5.0 Overall Thickness	600.00 +/- 26.00 $\mu$ m	ADE, 100%
	6.0 Total Thickness Variation (TTV)	<10.00 $\mu$ m	ADE, 100% measurement
	7.0 Bow	<40.00 $\mu$ m	ADE to ASTM F534, 20%
	8.0 Warp	<40.00 $\mu$ m	ADE to ASTM F657, 20%
	9.0 Edge Chips	0	Bright Light, 100% (note 2)
	10.0 Edge Exclusion	5mm	
HandleSilicon	11.0 Handle Growth Method	CZ	Wafer Vendor
	12.0 Handle Orientation	{100} +/- 1 degree	Wafer Vendor
	13.0 Handle Thickness	600.00 +/- 25.00 $\mu$ m	ADE, 100%
	14.0 Handle Doping Type	Any	Wafer Vendor
	15.0 Handle Dopant	Any	Wafer Vendor
	16.0 Handle Resistivity	> 0.0015 Ohmcm	Wafer Vendor
	17.0 Backside Finish	Deposited poly on oxide on Si with lasermark.	Guaranteed by process
	18.0 Backside Lasermark	On wafer BACKSIDE for identification. Scribe format: YYMM-XXXX (unique scribe)	
DeviceSilicon	19.0 Scratches	Total length <25mm	Bright Light, 100% (note 2)
	20.0 Haze	N/A = deposited polysilicon	Bright Light, 100% (note 2)
HandleSilicon	21.0 Handle Pad Oxide	10,000.00 +/- 1,000.00 A	Nanospec 9 point, 4%
HandleSilicon	22.0 Handle Polysilicon	20000A +/- 1000A, Phosphorous doped	Nanospec - 9 point.
BuriedOxide	23.0 Oxide Thickness	10.00 +/- 5.00 $\mu$ m	Nanospec - 9 point.

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Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	



Explanatory Notes 1. Microscope inspection performed using microscope scan as below. 5x objective.

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information